



北京大学  
PEKING UNIVERSITY

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# 人工智能与芯片设计

6- Design Flow (一款数字处理器芯片的诞生)

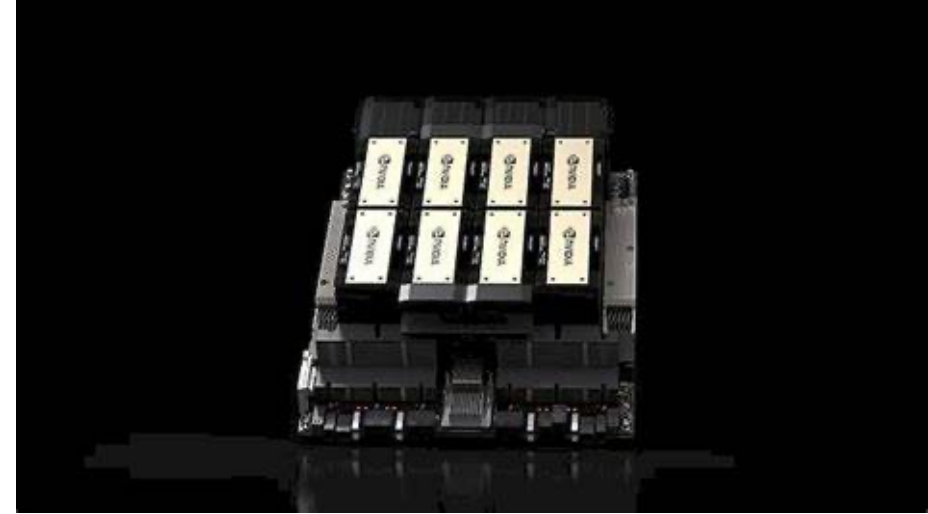
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2023秋

# Outline

- Design Partitioning
- MIPS Processor Example
  - Architecture
  - Microarchitecture
  - Logic Design
  - Circuit Design
  - Physical Design
- Fabrication, Packaging, Testing

# Coping with Complexity

- How to design System-on-Chip?
  - Many millions (even billions!) of transistors
  - Tens to hundreds of engineers
- Structured Design
- Design Partitioning



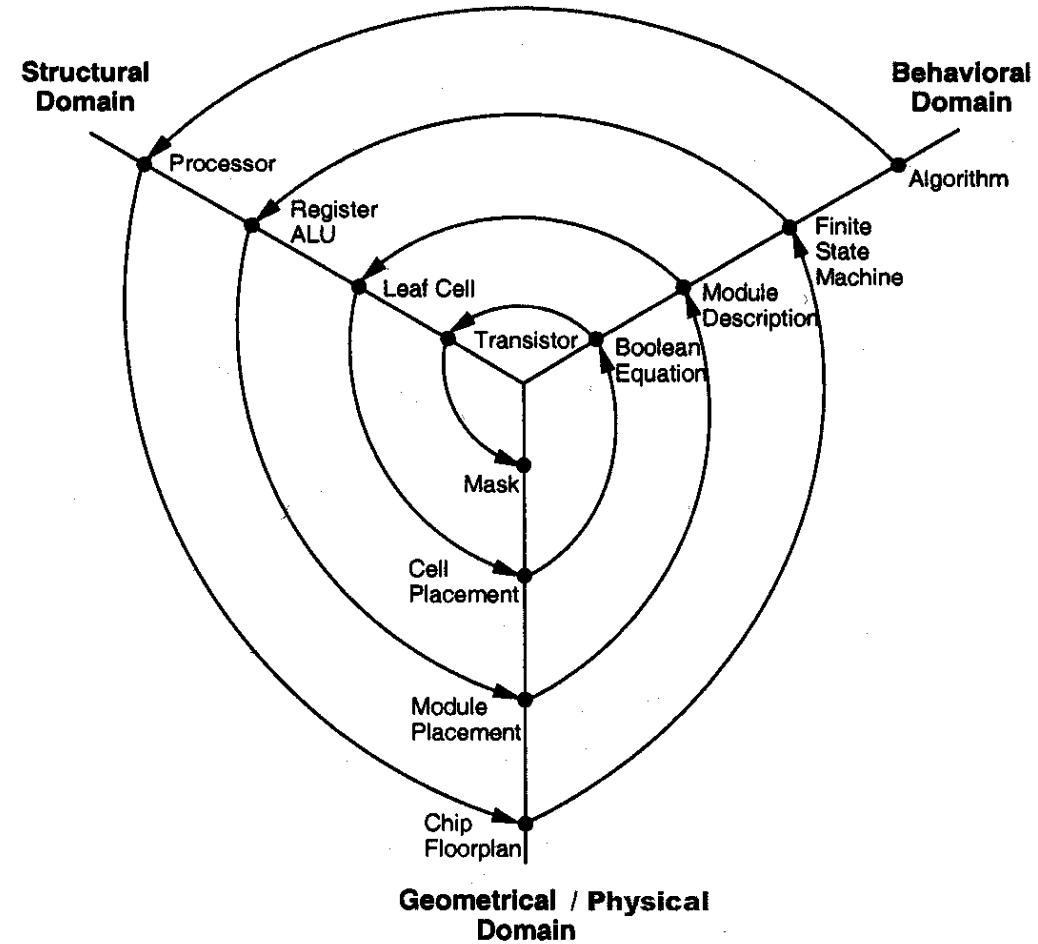
# Structured Design

- **Hierarchy: Divide and Conquer**
  - Recursively system into modules
- **Regularity**
  - Reuse modules wherever possible
  - Ex: Standard cell library
- **Modularity: well-formed interfaces**
  - Allows modules to be treated as black boxes
- **Locality**
  - Physical and temporal

# Design Partitioning

- **Architecture:** User's perspective, what does it do?
  - Instruction set, registers
  - MIPS, x86, Alpha, PIC, ARM, ...
- **Microarchitecture**
  - Single cycle, multicycle, pipelined, superscalar?
- **Logic:** how are functional blocks constructed
  - Ripple carry, carry lookahead, carry select adders
- **Circuit:** how are transistors used
  - Complementary CMOS, pass transistors, domino
- **Physical:** chip layout
  - Datapaths, memories, random logic

# Gajski Y-Chart



# MIPS Architecture

- Microprocessor without Interlocked Pipeline Stages
- MIPS is a 32-bit architecture with 32 registers
  - Consider 8-bit subset using 8-bit datapath
  - Only implement 8 registers (\$0 - \$7)
  - \$0 hardwired to 00000000
  - 8-bit program counter
- Predecessor of RISC-V

# Instruction Set

Table 1.7 MIPS instruction set (subset supported)				
Instruction	Function	Encoding	op	funct
add \$1, \$2, \$3	addition: \$1 → \$2 + \$3	R	000000	100000
sub \$1, \$2, \$3	subtraction: \$1 → \$2 - \$3	R	000000	100010
and \$1, \$2, \$3	bitwise and: \$1 → \$2 and \$3	R	000000	100100
or \$1, \$2, \$3	bitwise or: \$1 → \$2 or \$3	R	000000	100101
slt \$1, \$2, \$3	set less than: \$1 → 1 if \$2 < \$3 \$1 → 0 otherwise	R	000000	101010
addi \$1, \$2, imm	add immediate: \$1 → \$2 + imm	I	001000	n/a
beq \$1, \$2, imm	branch if equal: PC → PC + imm <sup>a</sup>	I	000100	n/a
j destination	jump: PC_destination <sup>a</sup>	J	000010	n/a
lb \$1, imm(\$2)	load byte: \$1 → mem[\$2 + imm]	I	100000	n/a
sb \$1, imm(\$2)	store byte: mem[\$2 + imm] → \$1	I	110000	n/a



# Instruction Encoding

- 32-bit instruction encoding
  - Requires four cycles to fetch on 8-bit datapath

format	example	encoding					
R	add \$rd, \$ra, \$rb	6	5	5	5	5	6
		0	ra	rb	rd	0	funct
I	beq \$ra, \$rb, imm	6	5	5	16		
		op	ra	rb	imm		
J	j dest	6	26				
		op	dest				

# Fibonacci (C)

$$f_0 = 1; f_{-1} = -1$$

$$f_n = f_{n-1} + f_{n-2}$$

$$f = 1, 1, 2, 3, 5, 8, 13, \dots$$

```
int fib(void)
{
    int n = 8;          /* compute nth Fibonacci number */
    int f1 = 1, f2 = -1; /* last two Fibonacci numbers */

    while (n != 0) {   /* count down to n = 0 */
        f1 = f1 + f2;
        f2 = f1 - f2;
        n = n - 1;
    }
    return f1;
}
```

# Fibonacci (Assembly)

- 1<sup>st</sup> statement:  $n = 8$
- How do we translate this to assembly?

```
# fib.asm
# Register usage: $3: n $4: f1 $5: f2
# return value written to address 255
fib:  addi $3, $0, 8      # initialize n=8
      addi $4, $0, 1     # initialize f1 = 1
      addi $5, $0, -1   # initialize f2 = -1
loop: beq $3, $0, end   # Done with loop if n = 0
      add $4, $4, $5    # f1 = f1 + f2
      sub $5, $4, $5    # f2 = f1 - f2
      addi $3, $3, -1   # n = n - 1
      j loop           # repeat until done
end:  sb $4, 255($0)    # store result in address 255
```

# Fibonacci (Binary)

- 1<sup>st</sup> statement: addi \$3, \$0, 8
- How do we translate this to machine language?
  - Hint: use instruction encodings below

format	example	encoding					
R	add \$rd, \$ra, \$rb	6 0	5 ra	5 rb	5 rd	5 0	6 funct
I	beq \$ra, \$rb, imm	6 op	5 ra	5 rb	16 imm		
J	j dest	6 op	26 dest				

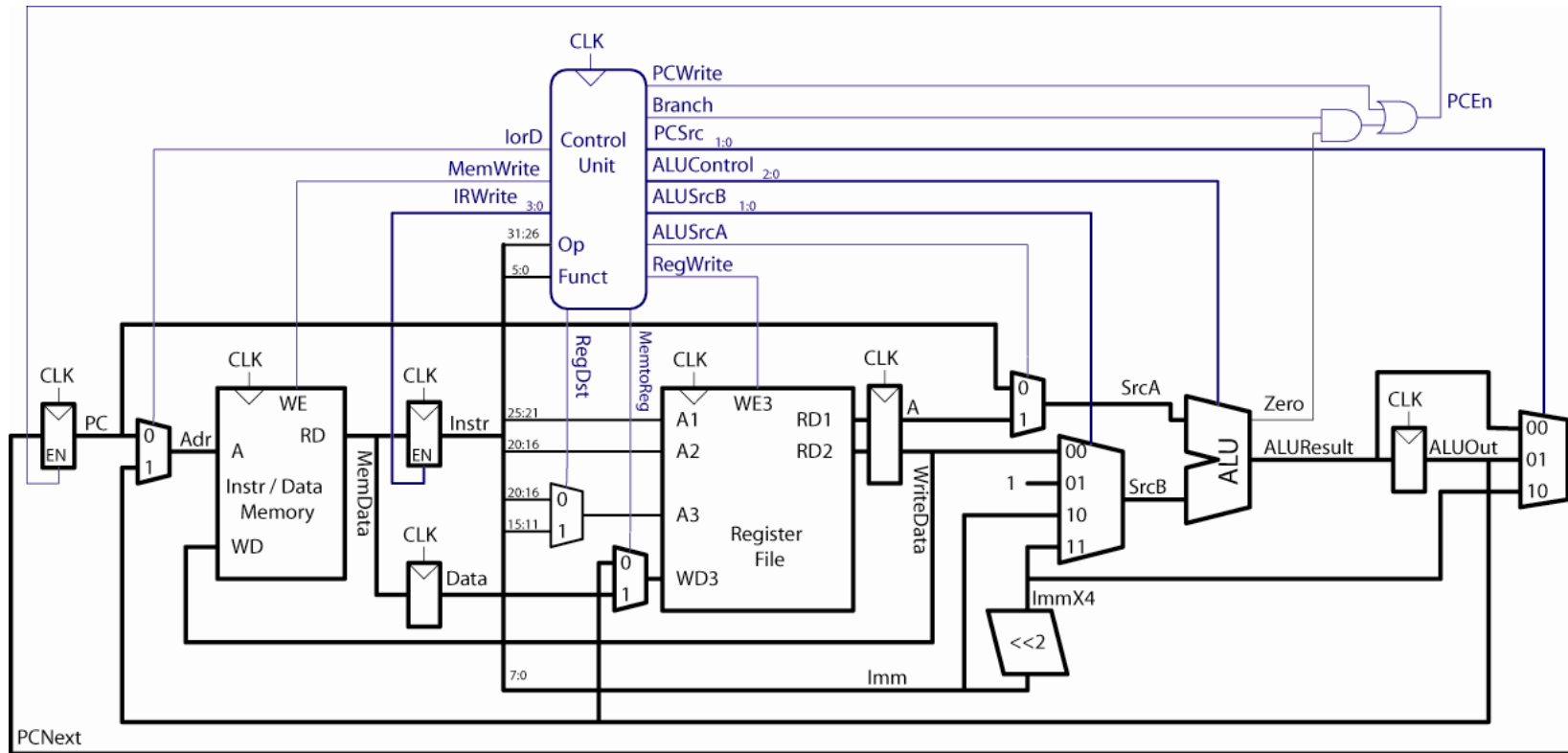
# Fibonacci (Binary)

- Machine language program

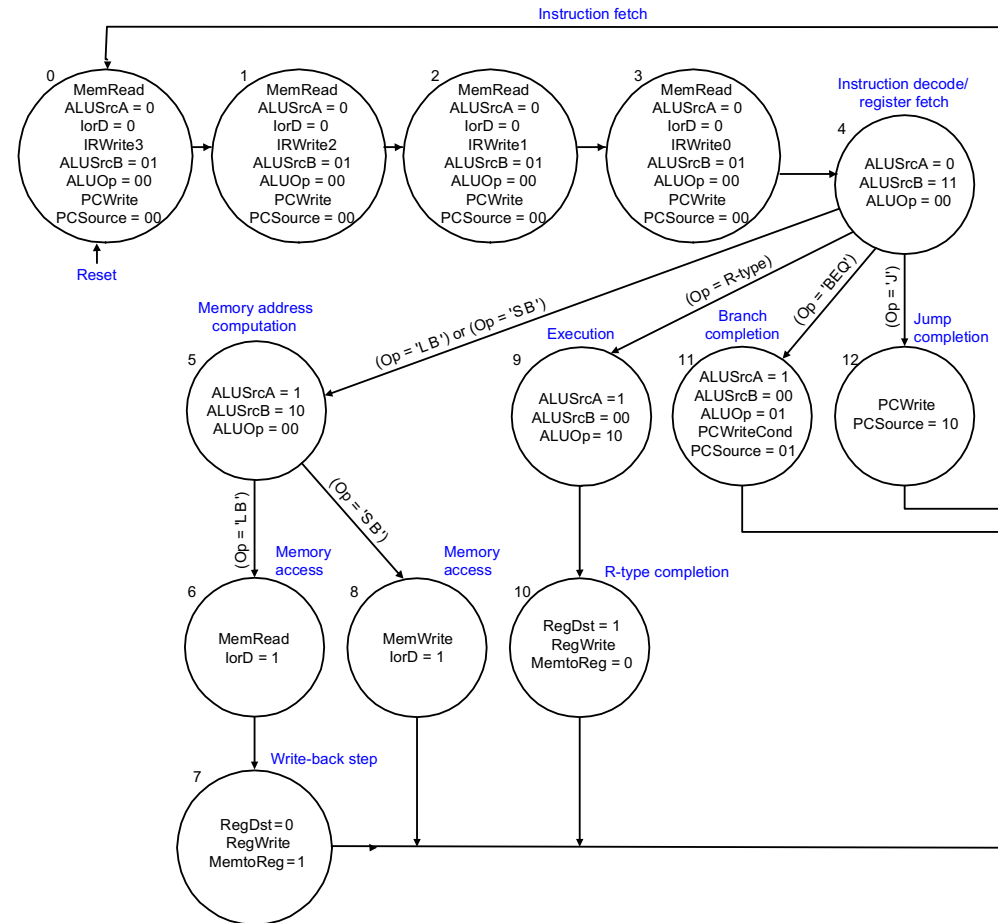
<b>Instruction</b>	<b>Binary Encoding</b>	<b>Hexadecimal Encoding</b>
addi \$3, \$0, 8	001000 00000 00011 0000000000001000	20030008
addi \$4, \$0, 1	001000 00000 00100 0000000000000001	20040001
addi \$5, \$0, -1	001000 00000 00101 1111111111111111	2005ffff
beq \$3, \$0, end	000100 00011 00000 00000000000000101	10600005
add \$4, \$4, \$5	000000 00100 00101 00100 00000 100000	00852020
sub \$5, \$4, \$5	000000 00100 00101 00101 00000 100010	00852822
addi \$3, \$3, -1	001000 00011 00011 1111111111111111	2063ffff
j loop	000010 00000000000000000000000000000011	08000003
sb \$4, 255(\$0)	110000 00000 00100 0000000011111111	a00400ff

# MIPS Microarchitecture

- Multicycle  $\mu$ architecture ( [Paterson04], [Harris07] )

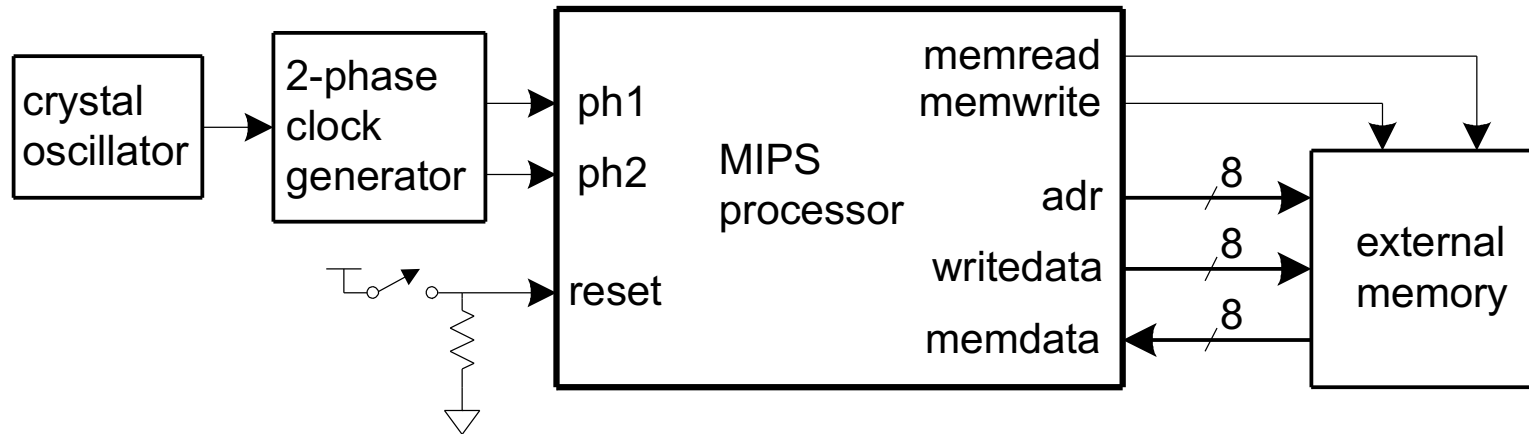


# Multicycle Controller



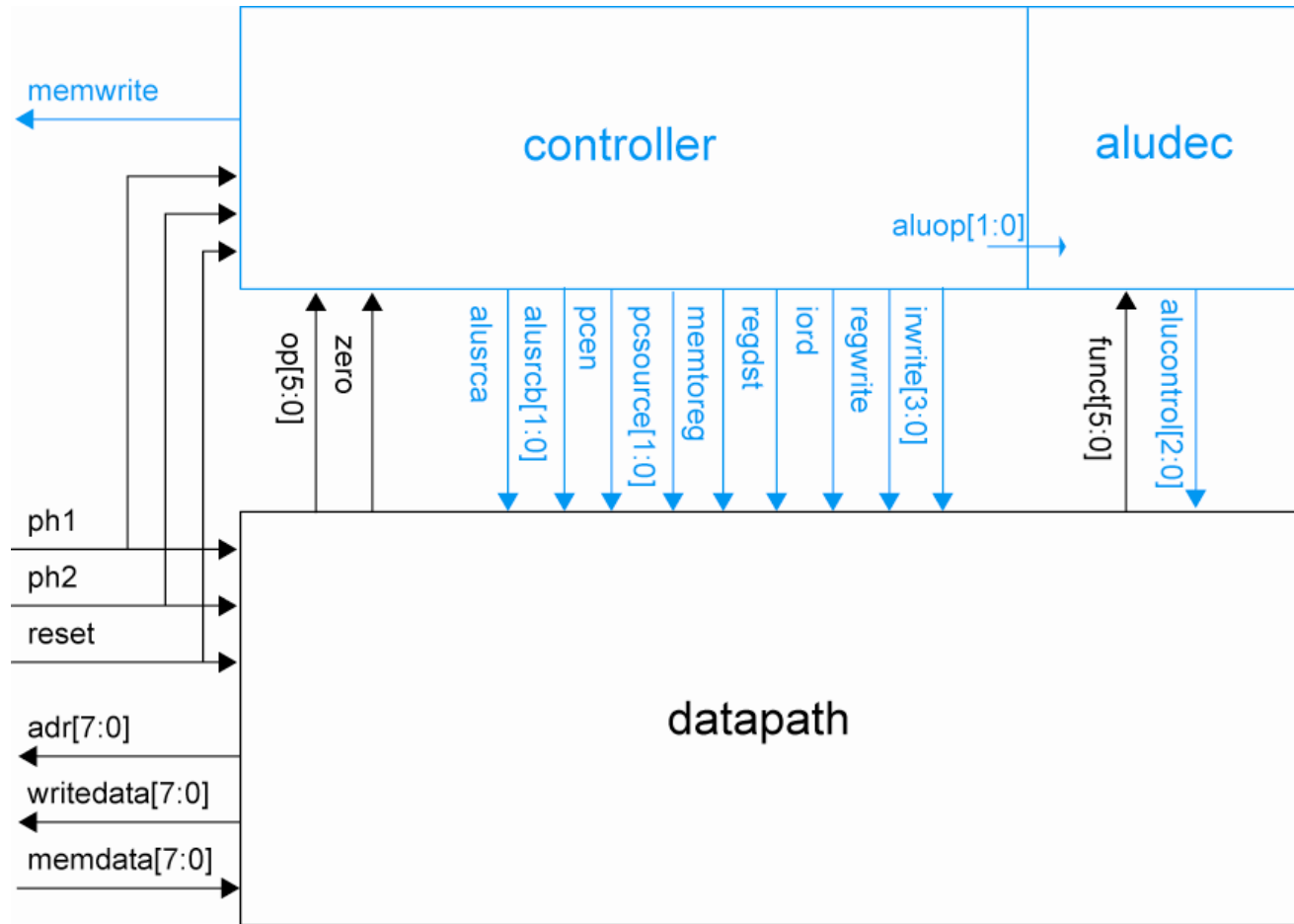
# Logic Design

- Start at top level
  - Hierarchically decompose MIPS into units
- Top-level interface

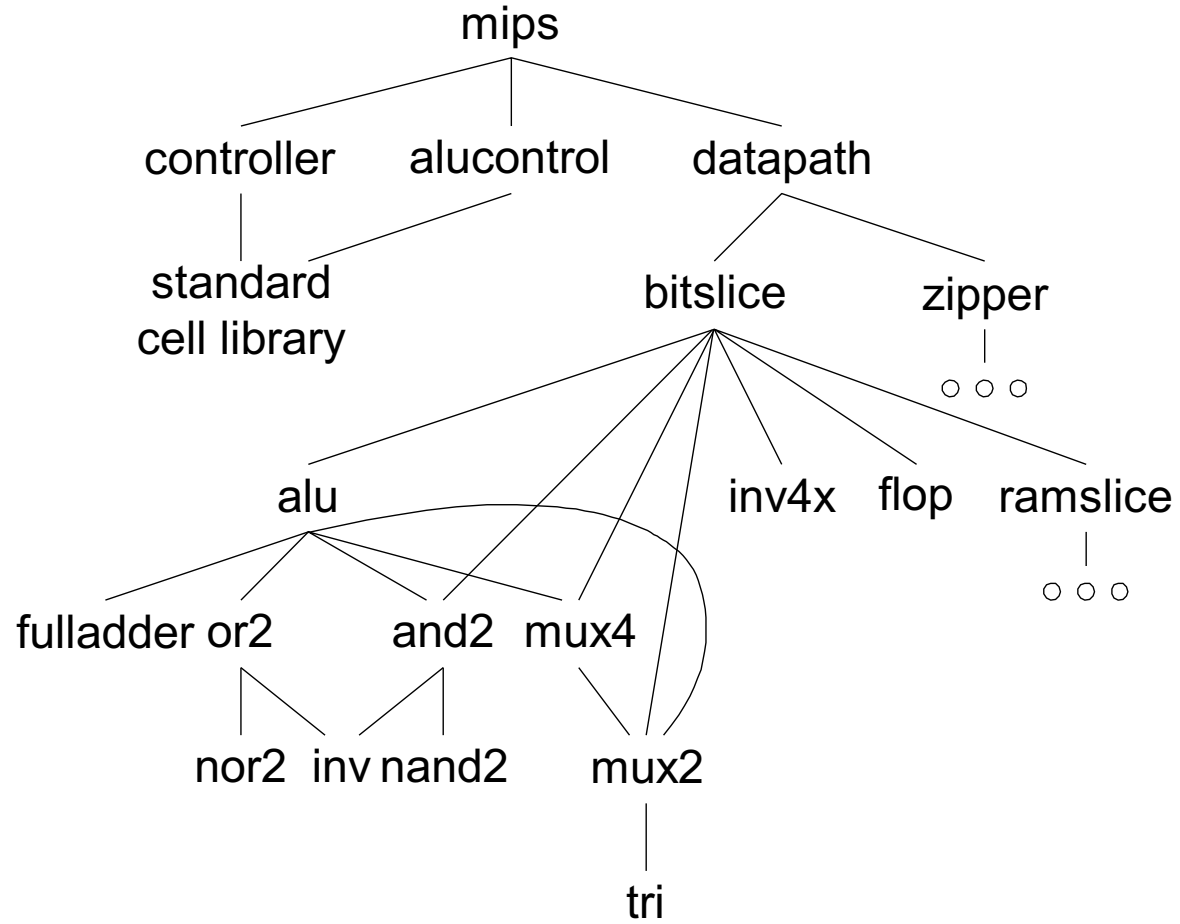




# Block Diagram



# Hierarchical Design



# HDLs

- Hardware Description Languages
  - Widely used in logic design
  - Verilog, VHDL, Chisel HGL
- Describe hardware using code
  - Document logic functions
  - Simulate logic before building
  - Synthesize code into gates and layout
    - Requires a library of standard cells

# Verilog Example

```
module fulladder(input a, b, c,  
                output s, cout);
```

```
    sum          s1(a, b, c, s);
```

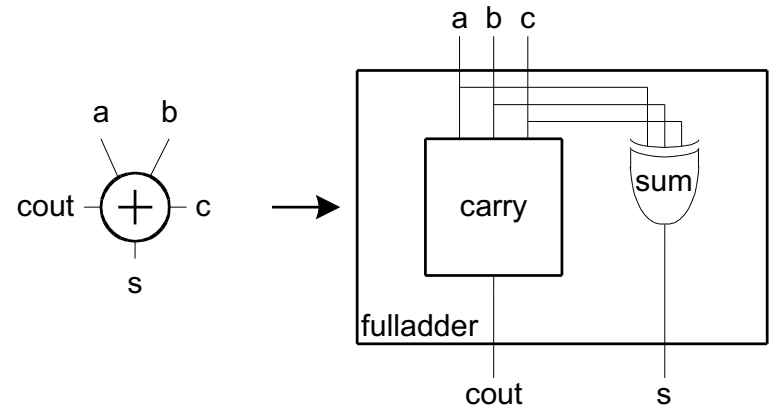
```
    carry        c1(a, b, c, cout);
```

```
endmodule
```

```
module carry(input a, b, c,  
            output cout)
```

```
    assign cout = (a&b) | (a&c) | (b&c);
```

```
endmodule
```

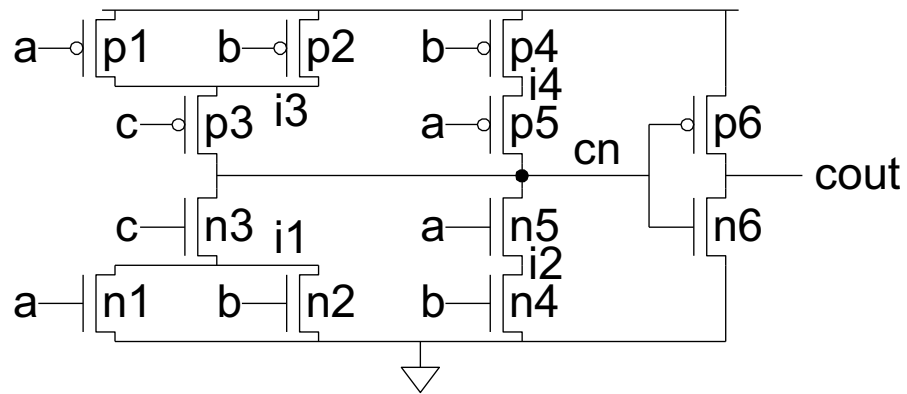
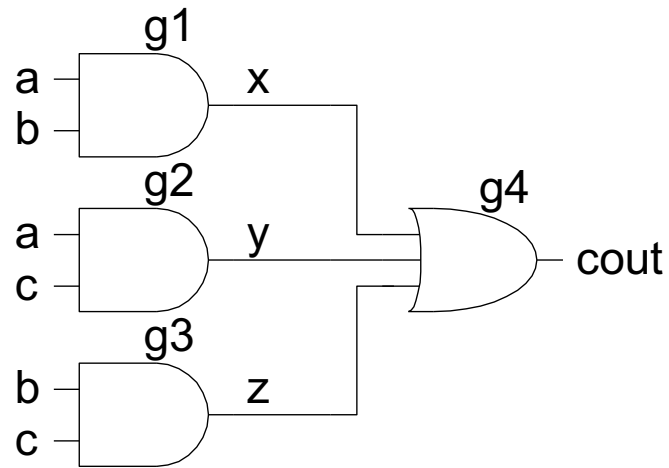


# Circuit Design

- How should logic be implemented?
  - NANDs and NORs vs. ANDs and ORs?
  - Fan-in and fan-out?
  - How wide should transistors be?
- These choices affect speed, area, power
- Logic synthesis makes these choices for you
  - Good enough for many applications
  - Hand-crafted circuits are still better

# Example: Carry Logic

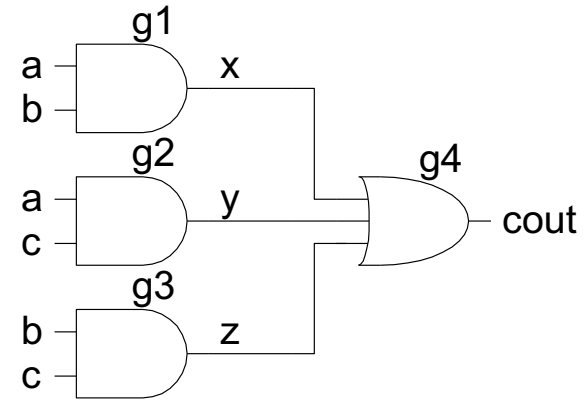
- **assign** cout = (a&b) | (a&c) | (b&c);



Transistors? Gate Delays?

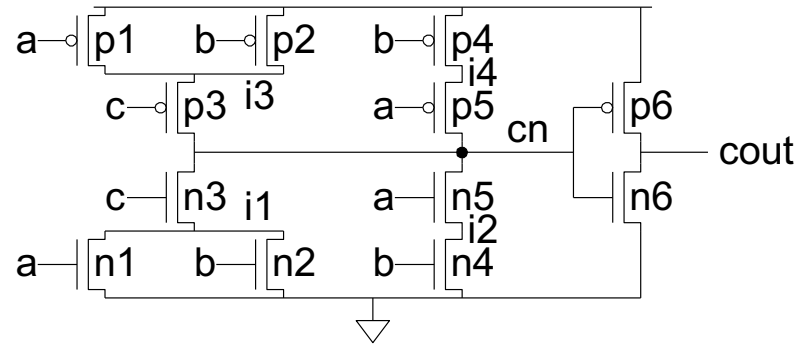
# Gate-level Netlist

```
module carry(input  a, b, c,  
              output cout)  
  
    wire      x, y, z;  
  
    and g1(x, a, b);  
    and g2(y, a, c);  
    and g3(z, b, c);  
    or  g4(cout, x, y, z);  
endmodule
```



# Transistor-Level Netlist

```
module carry(input a, b, c,  
            output cout)  
  
    wire i1, i2, i3, i4, cn;  
  
    tranif1 n1(i1, 0, a);  
    tranif1 n2(i1, 0, b);  
    tranif1 n3(cn, i1, c);  
    tranif1 n4(i2, 0, b);  
    tranif1 n5(cn, i2, a);  
    tranif0 p1(i3, 1, a);  
    tranif0 p2(i3, 1, b);  
    tranif0 p3(cn, i3, c);  
    tranif0 p4(i4, 1, b);  
    tranif0 p5(cn, i4, a);  
    tranif1 n6(cout, 0, cn);  
    tranif0 p6(cout, 1, cn);  
endmodule
```



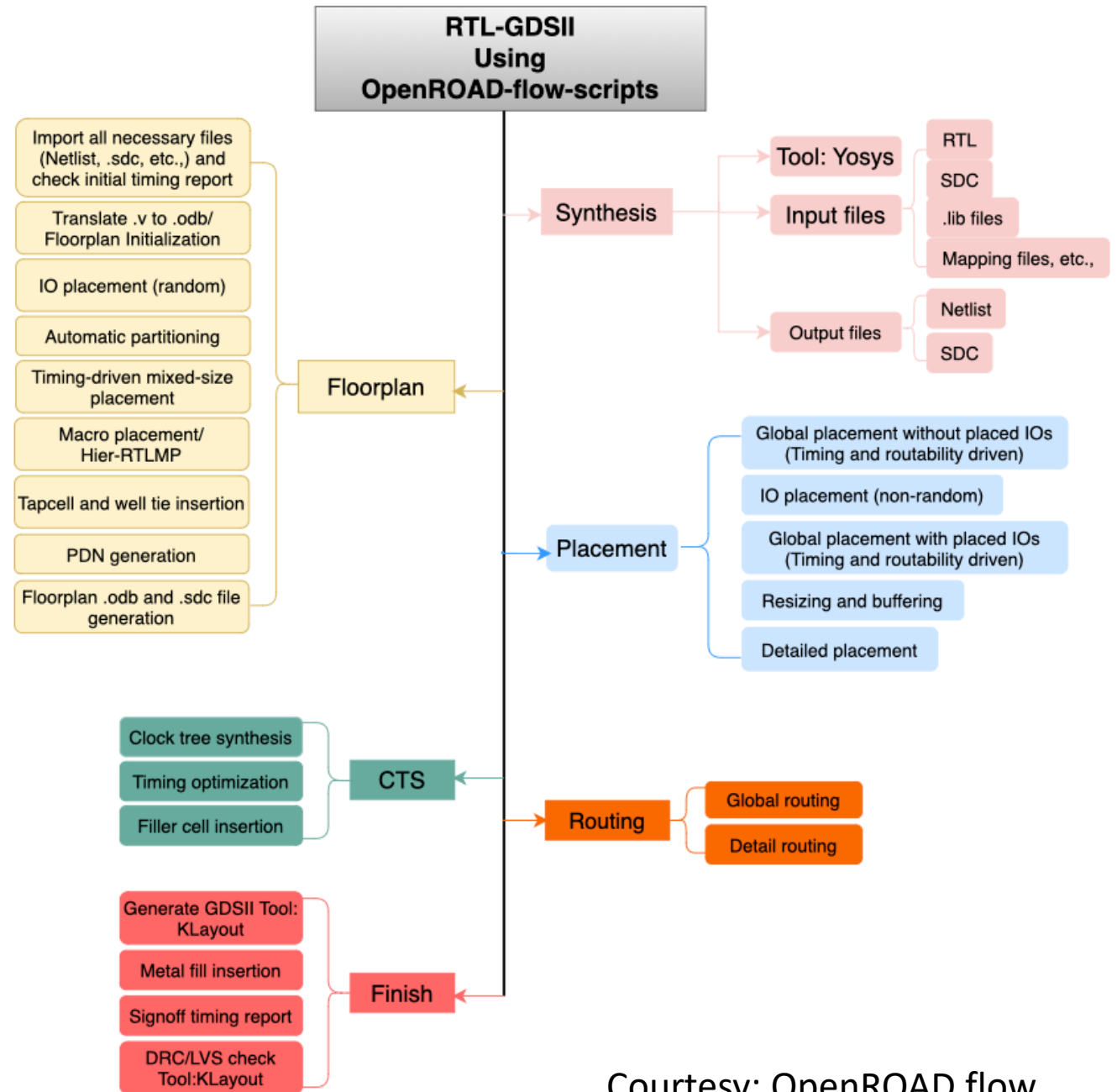


# SPICE Netlist

```
.SUBCKT CARRY A B C COUT VDD GND
MN1 I1 A GND GND NMOS W=1U L=0.18U AD=0.3P AS=0.5P
MN2 I1 B GND GND NMOS W=1U L=0.18U AD=0.3P AS=0.5P
MN3 CN C I1 GND NMOS W=1U L=0.18U AD=0.5P AS=0.5P
MN4 I2 B GND GND NMOS W=1U L=0.18U AD=0.15P AS=0.5P
MN5 CN A I2 GND NMOS W=1U L=0.18U AD=0.5P AS=0.15P
MP1 I3 A VDD VDD PMOS W=2U L=0.18U AD=0.6P AS=1 P
MP2 I3 B VDD VDD PMOS W=2U L=0.18U AD=0.6P AS=1P
MP3 CN C I3 VDD PMOS W=2U L=0.18U AD=1P AS=1P
MP4 I4 B VDD VDD PMOS W=2U L=0.18U AD=0.3P AS=1P
MP5 CN A I4 VDD PMOS W=2U L=0.18U AD=1P AS=0.3P
MN6 COUT CN GND GND NMOS W=2U L=0.18U AD=1P AS=1P
MP6 COUT CN VDD VDD PMOS W=4U L=0.18U AD=2P AS=2P
CI1 I1 GND 2FF
CI3 I3 GND 3FF
CA A GND 4FF
CB B GND 4FF
CC C GND 2FF
CCN CN GND 4FF
CCOUT COUT GND 2FF
.ENDS
```

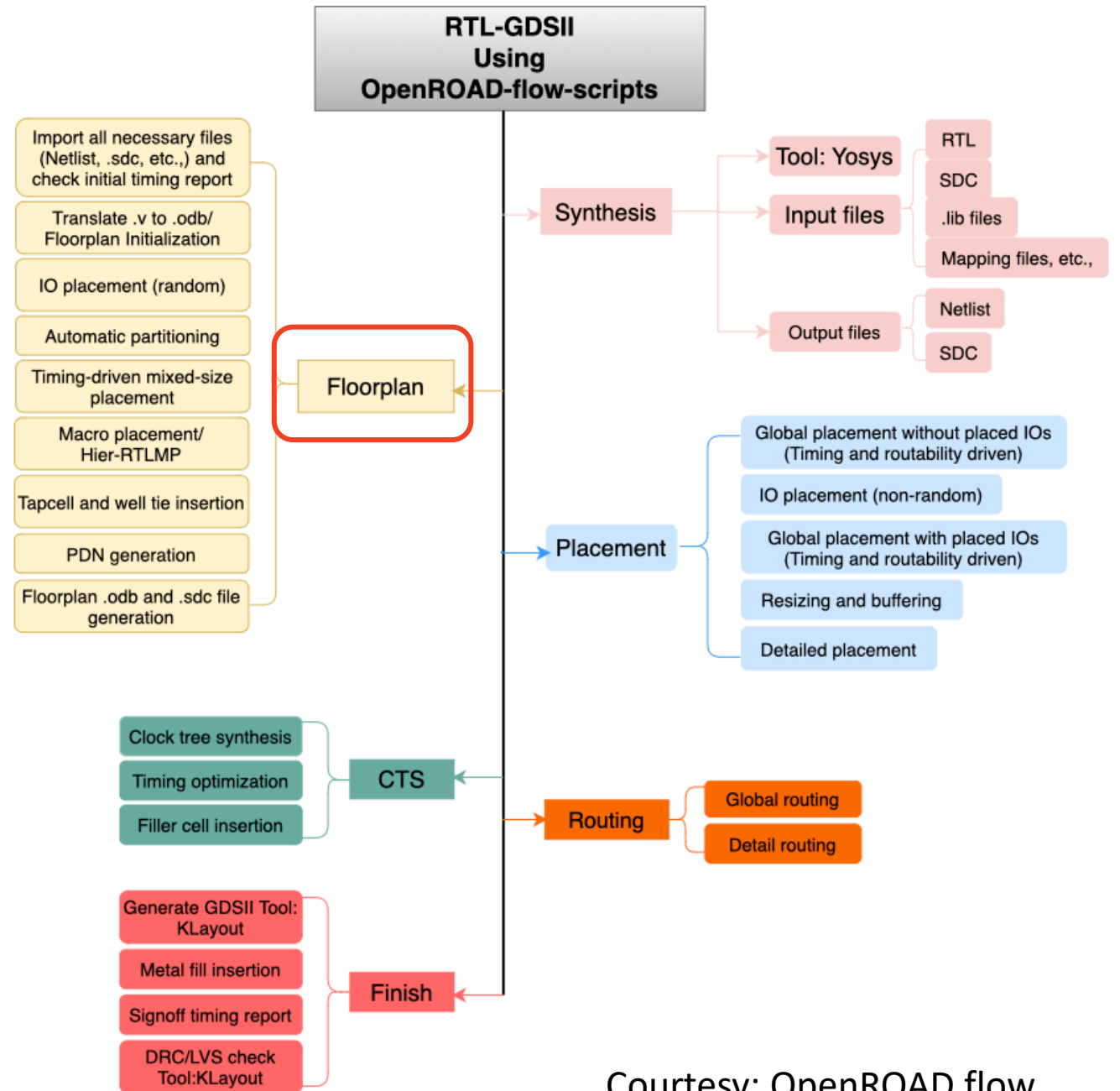
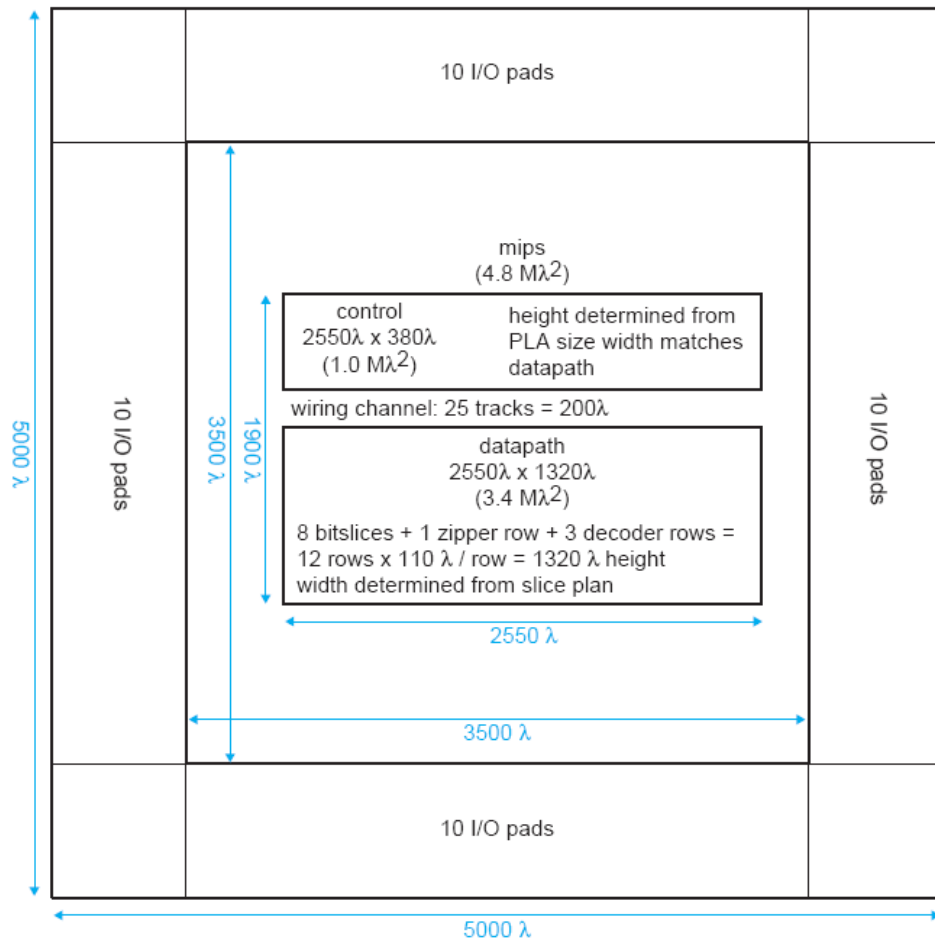
# Physical Design

- Synthesis: Behavioral to Gate-Level Netlist
- Floorplan: Define Blocks (Modules in Verilog) on a chip
- Placement: Place Gate Cells
- CTS: Clock tree synthesis, generate clock tree
- Routing: connect all wires
- Physical Verification:
  - Timing Check
  - Post-Layout Simulation



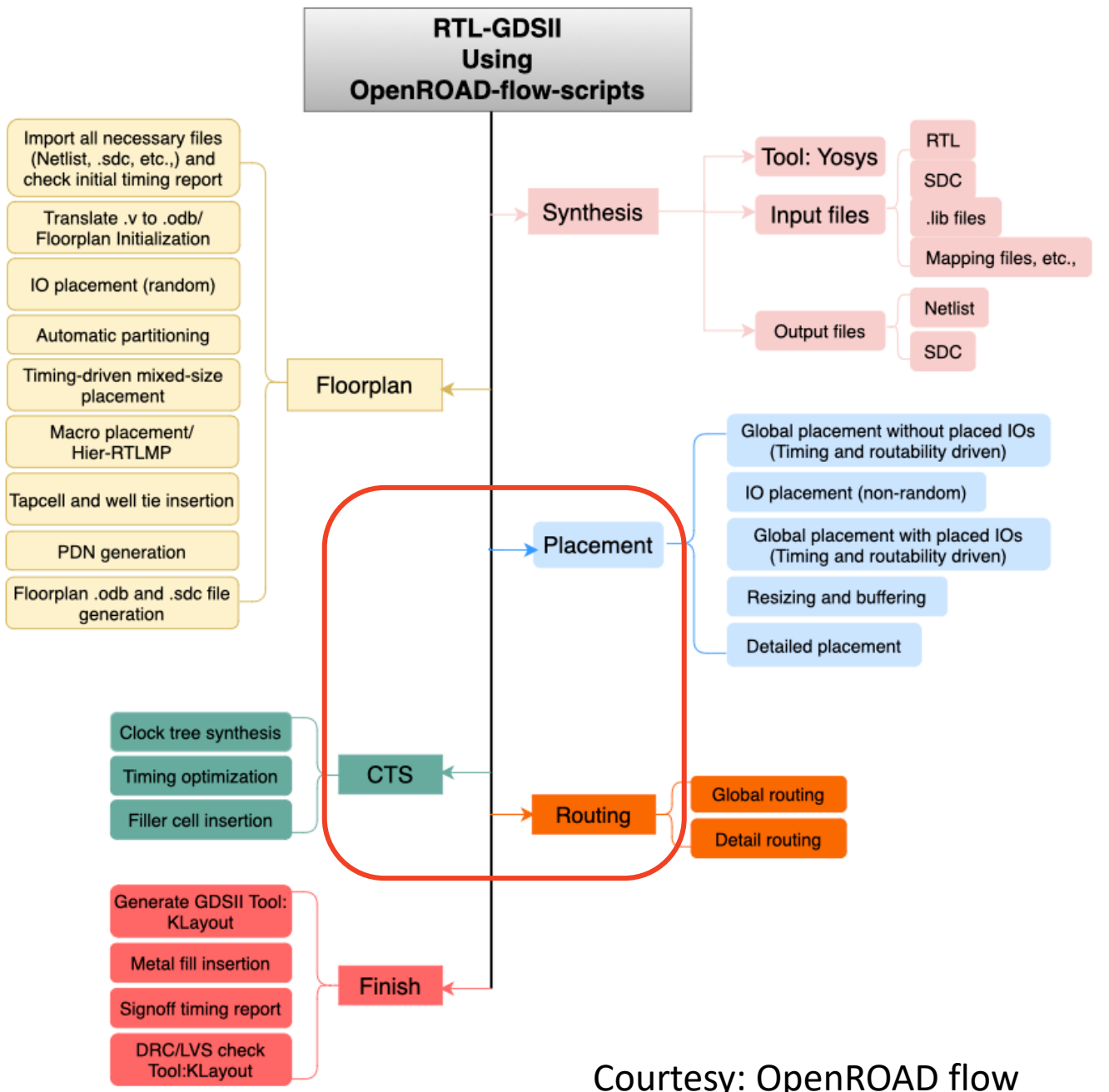
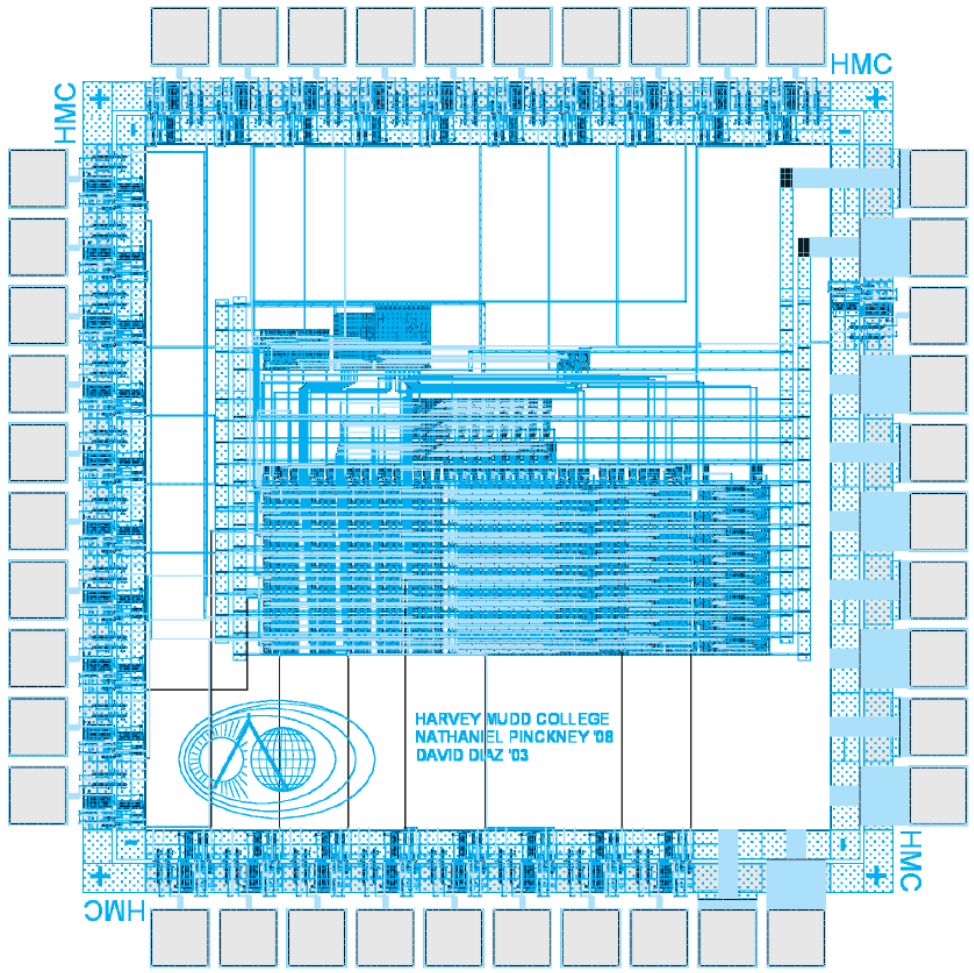
Courtesy: OpenROAD flow

# MIPS Floorplan



Courtesy: OpenROAD flow

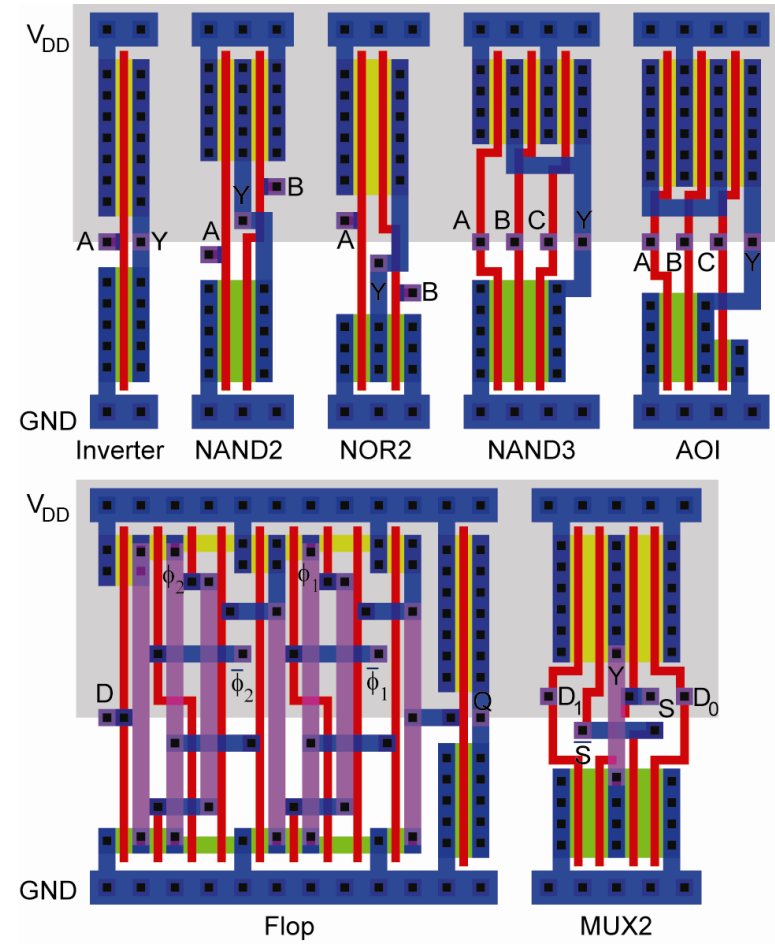
# MIPS Layout



Courtesy: OpenROAD flow

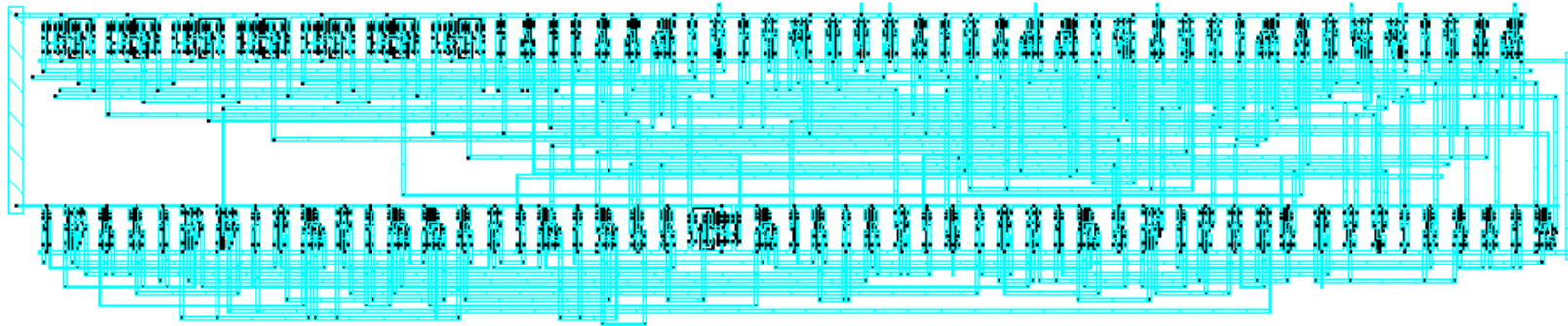
# Standard Cells

- Uniform cell height
- Uniform well height
- M1  $V_{DD}$  and GND rails
- M2 Access to I/Os
- Well / substrate taps
- Exploits regularity



# Synthesized Controller

- Synthesize HDL into gate-level netlist
- Place & Route using standard cell library



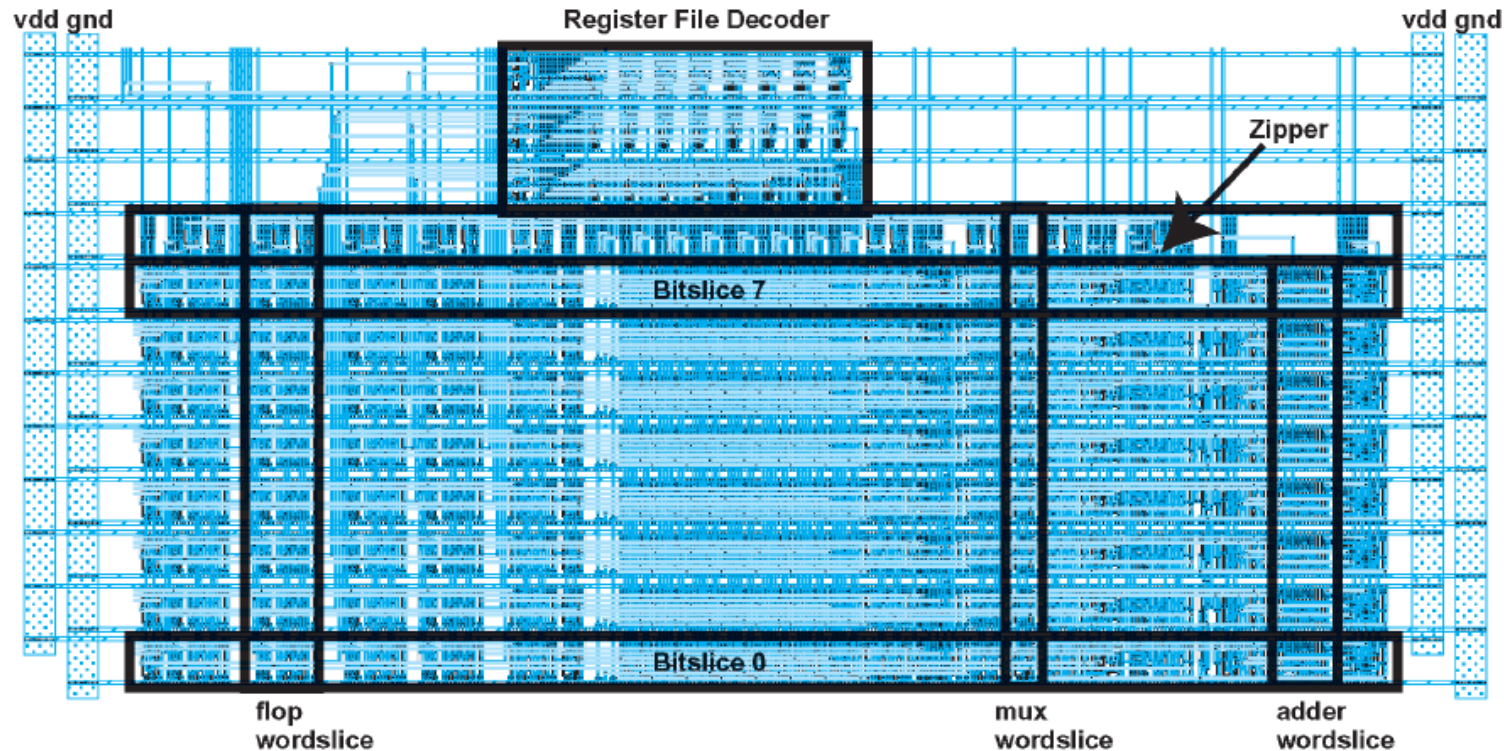
# Pitch Matching

- Synthesized controller area is mostly wires
  - Design is smaller if wires run through/over cells
  - Smaller = faster, lower power as well!
- Design snap-together cells for datapaths and arrays
  - Plan wires into cells
  - Connect by abutment
    - Exploits locality
    - Takes lots of effort

A	A	A	A	B
A	A	A	A	B
A	A	A	A	B
A	A	A	A	B
C		C		D

# MIPS Datapath

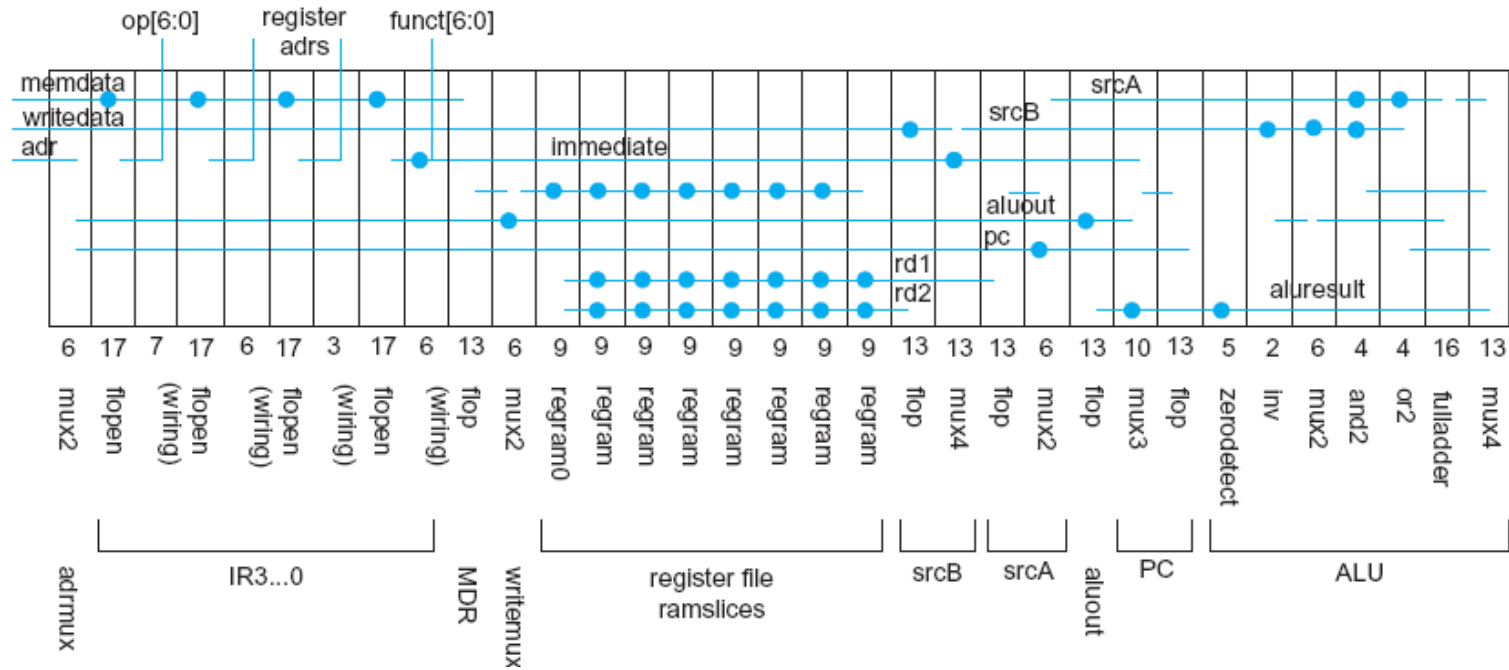
- 8-bit datapath built from 8 bitslices (regularity)
- Zipper at top drives control signals to datapath





# Slice Plans

- Slice plan for bitslice
  - Cell ordering, dimensions, wiring tracks
  - Arrange cells for wiring locality



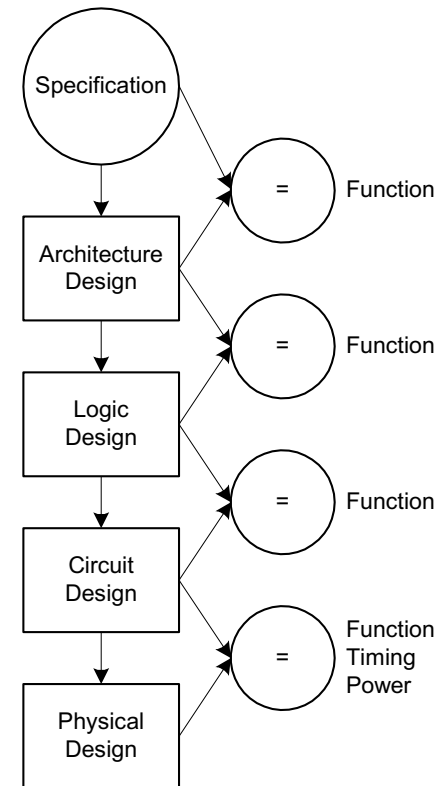
# Area Estimation

- Need area estimates to make floorplan
  - Compare to another block you already designed
  - Or estimate from transistor counts
  - Budget room for large wiring tracks
  - Your mileage may vary; derate by 2x for class.

Element	Area
random logic (2-level metal process)	1000 – 1500 $\lambda^2$ / transistor
datapath	250 – 750 $\lambda^2$ / transistor or 6 WL + 360 $\lambda^2$ / transistor
SRAM	1000 $\lambda^2$ / bit
DRAM (in a DRAM process)	100 $\lambda^2$ / bit
ROM	100 $\lambda^2$ / bit

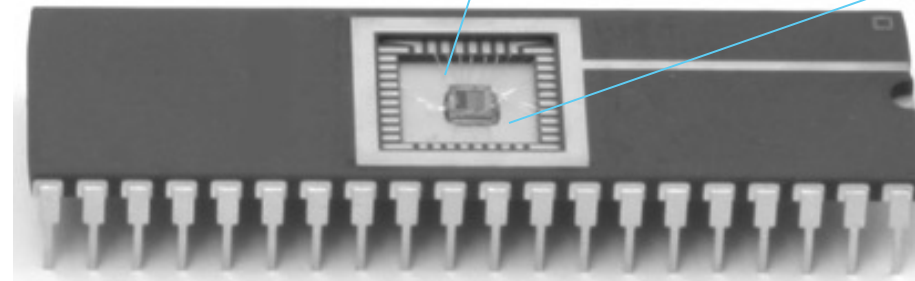
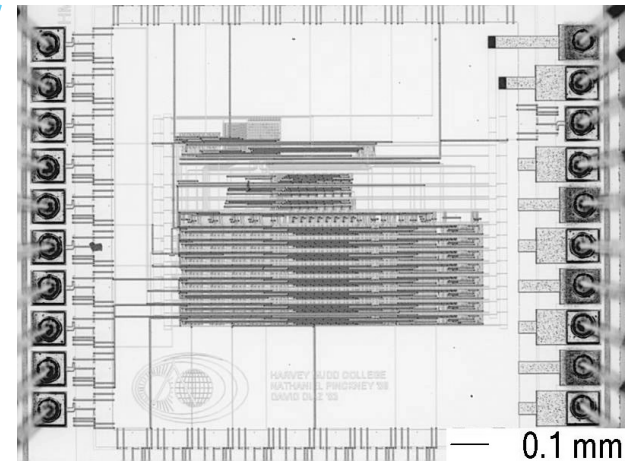
# Design Verification

- Fabrication is slow & expensive
  - MOSIS 0.6 $\mu$ m: \$1000, 3 months
  - 65 nm: \$3M, 1 month
- Debugging chips is very hard
  - Limited visibility into operation
- Prove design is right before building!
  - Logic simulation
  - Ckt. simulation / formal verification
  - Layout vs. schematic comparison
  - Design & electrical rule checks
- Verification is > 50% of effort on most chips!



# Fabrication & Packaging

- Tapeout final layout
- Fabrication
  - 6, 8, 12" wafers
  - Optimized for throughput, not latency (10 weeks!)
  - Cut into individual dice
- Packaging
  - Bond gold wires from die I/O pads to package

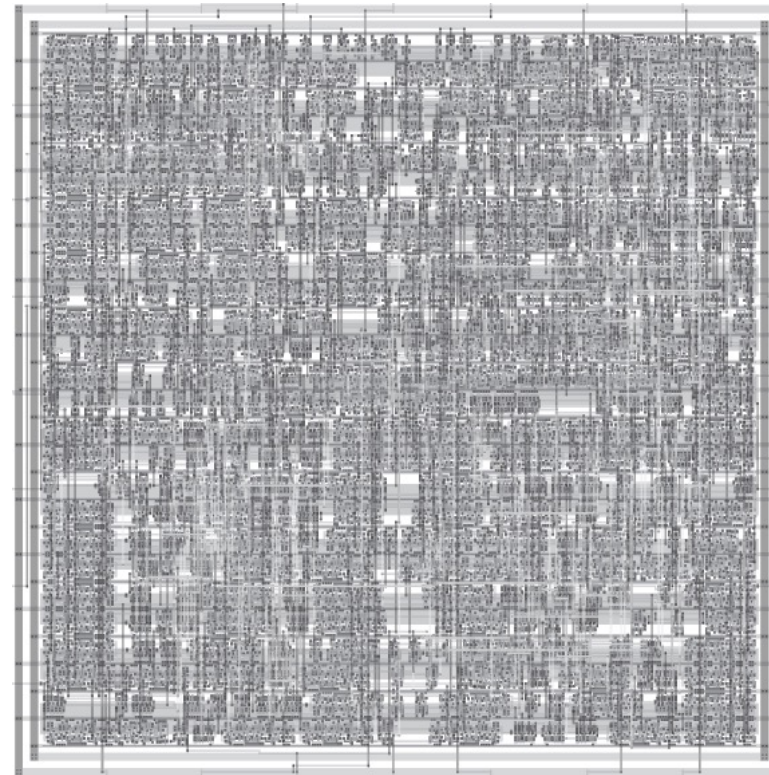
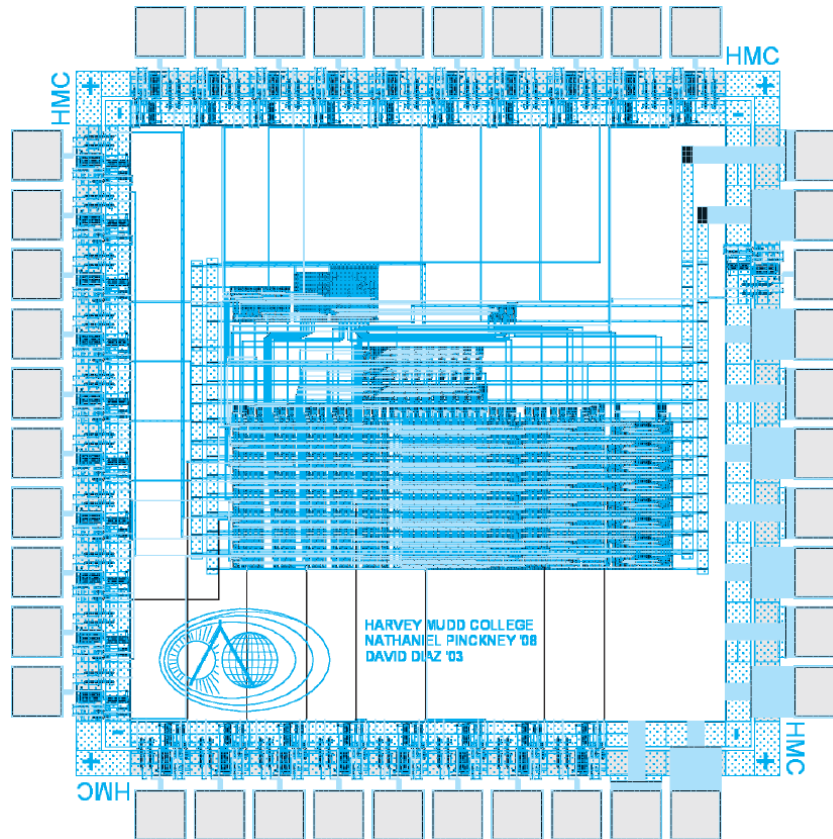


# Testing

- Test that chip operates
  - Design errors
  - Manufacturing errors
- A single dust particle or wafer defect kills a die
  - Yields from 90% to < 10%
  - Depends on die size, maturity of process
  - Test each part before shipping to customer

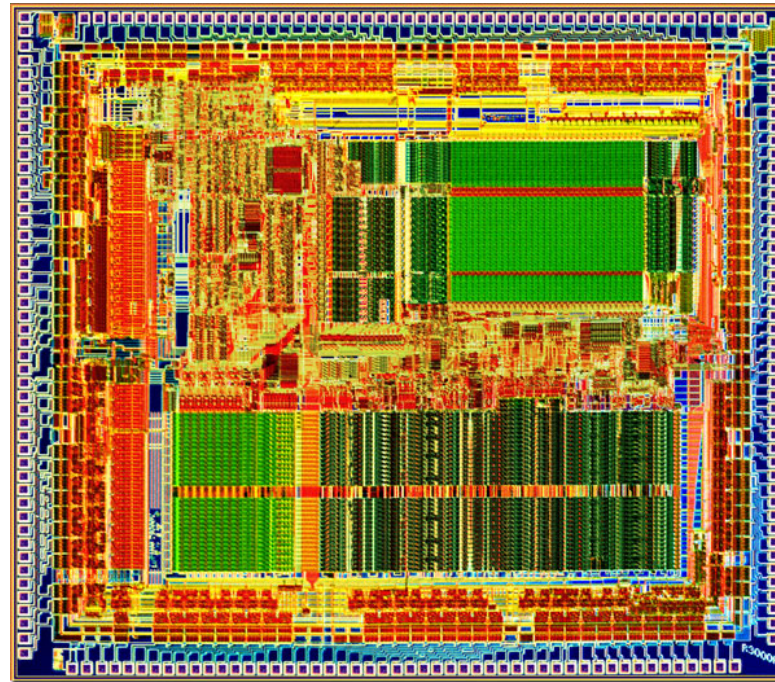
# Custom vs. Synthesis

## ❑ 8-bit Implementations



# MIPS R3000 Processor

- 32-bit 2<sup>nd</sup> generation commercial processor (1988)
- Led by John Hennessy (Stanford, MIPS Founder)
- 32-64 KB Caches
- 1.2  $\mu\text{m}$  process
- 111K Transistors
- Up to 12-40 MHz
- 66  $\text{mm}^2$  die
- 145 I/O Pins
- $V_{\text{DD}} = 5 \text{ V}$
- 4 Watts
- SGI Workstations



[http://gecko54000.free.fr/?documentations=1988\\_MIPS\\_R3000](http://gecko54000.free.fr/?documentations=1988_MIPS_R3000)

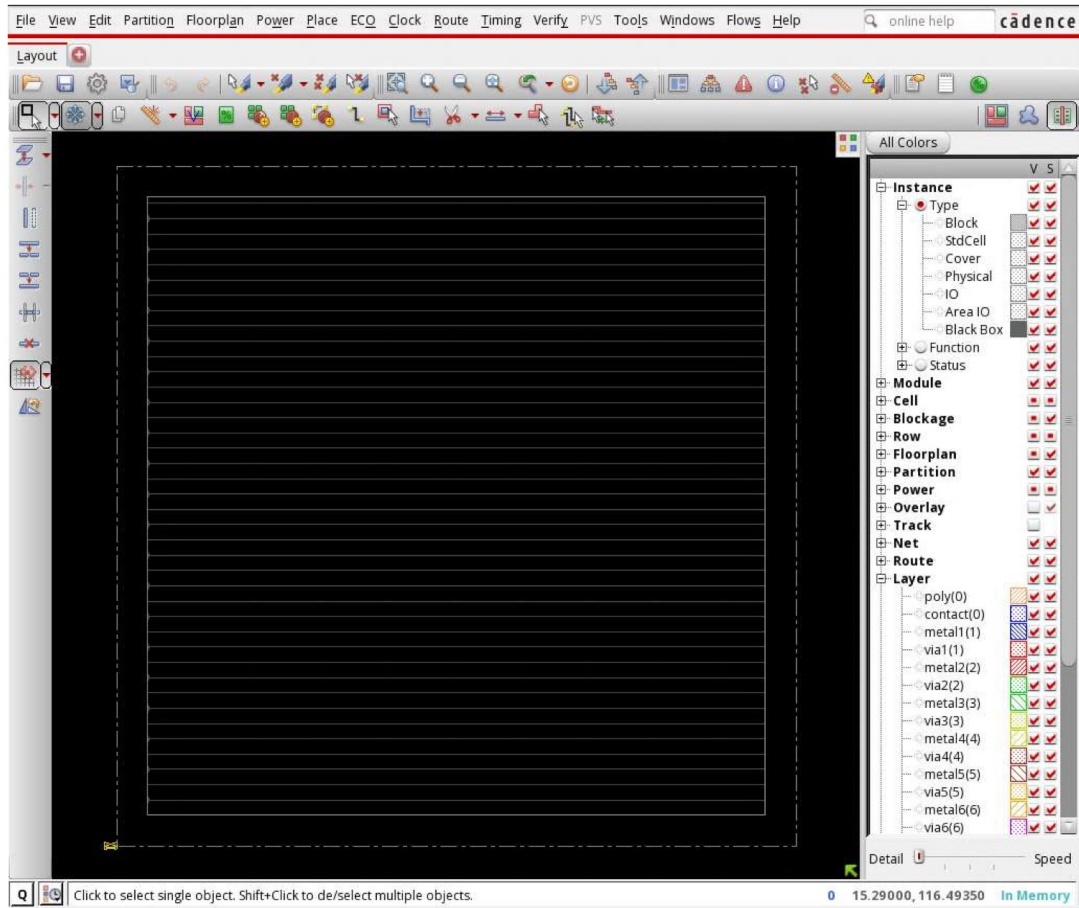
# Front-End and Back-End Examples

- Logic Synthesis Example
- Physical Synthesis Example

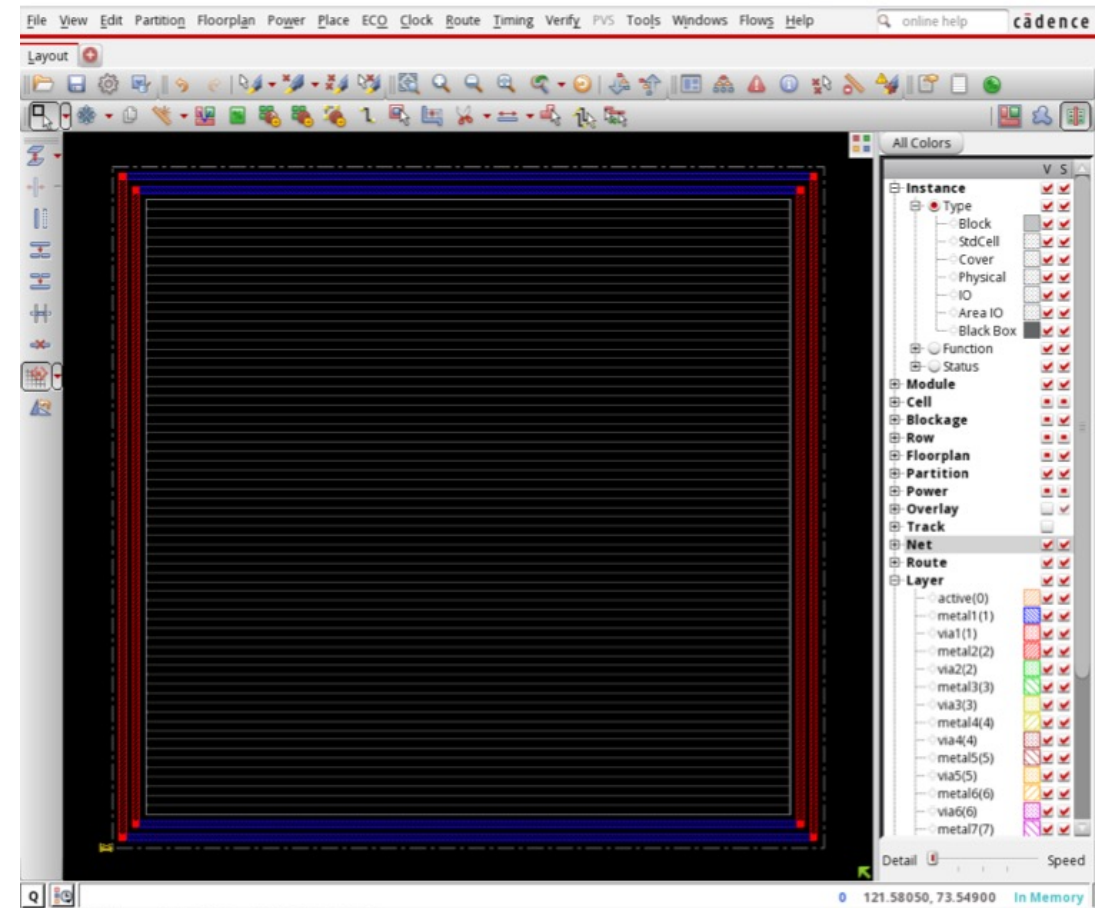


# Example of Back-end Design (Physical Design)

Initial

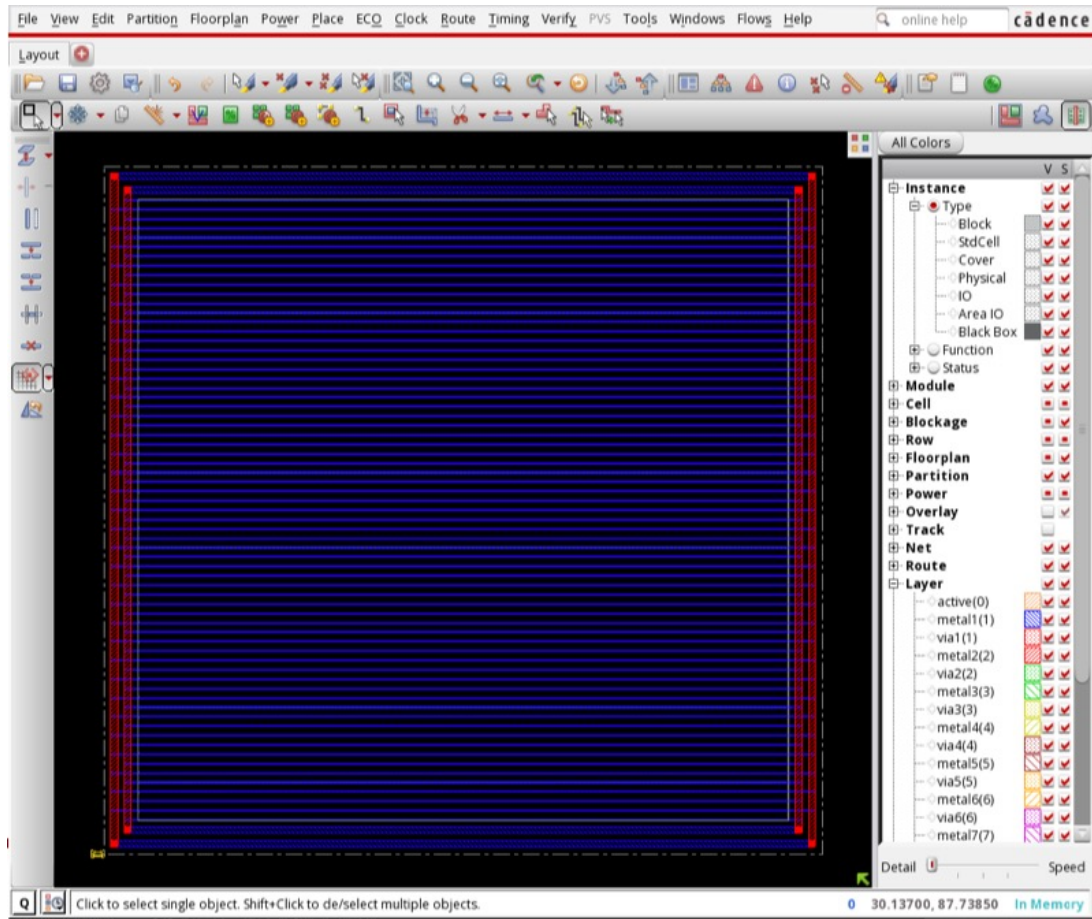


Place Power Ring

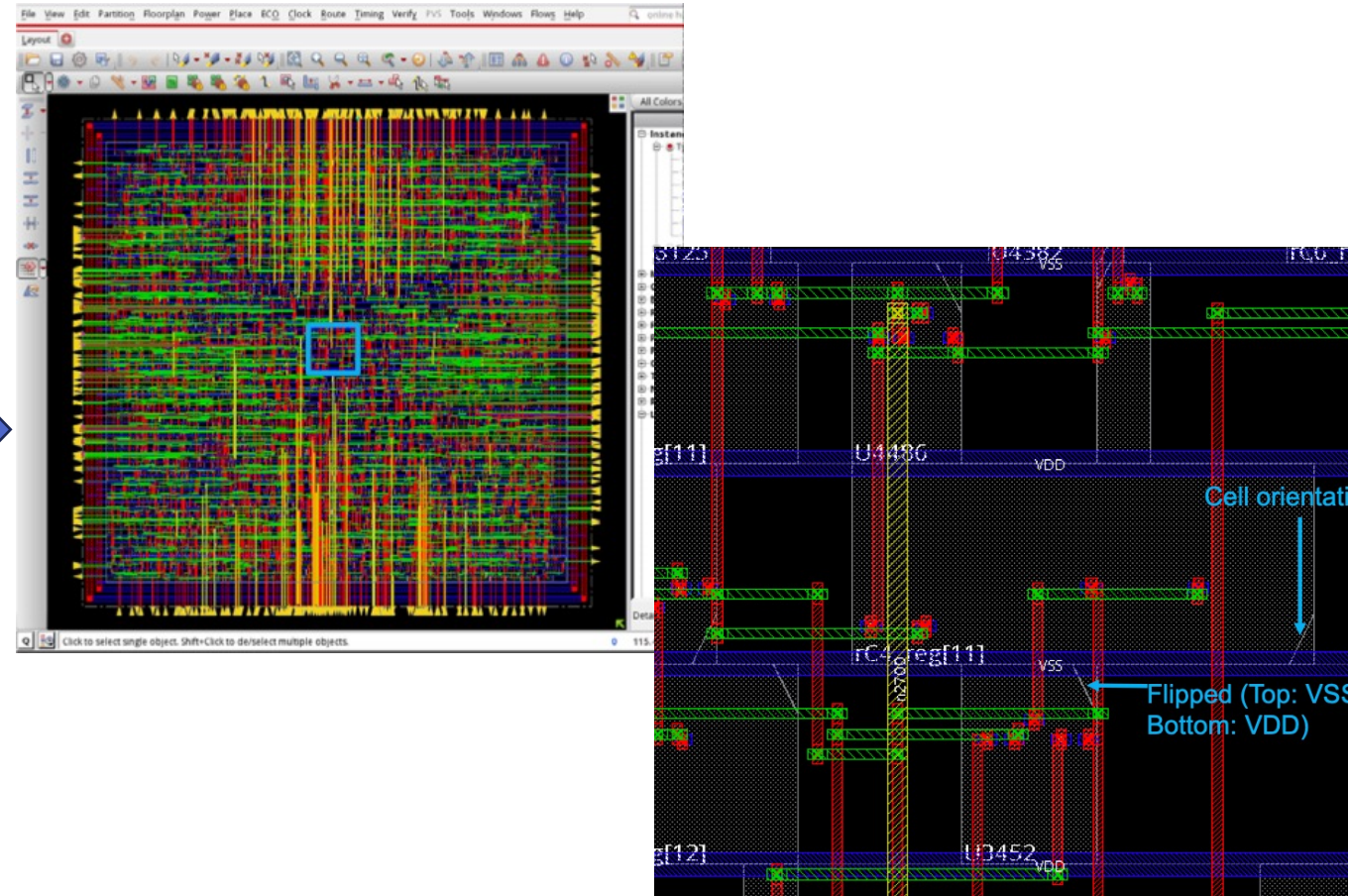


# Example of Back-end Design (Physical Design)

Place Power Rail

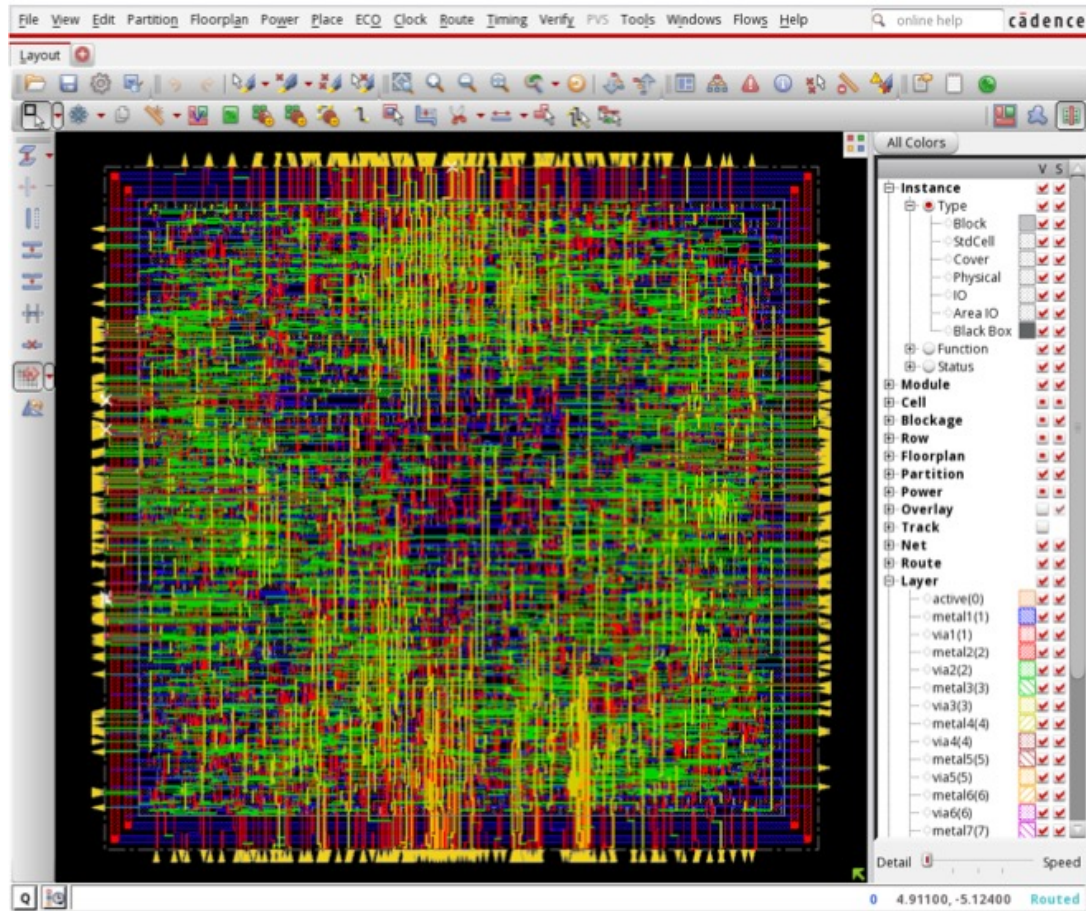


Place Power Ring

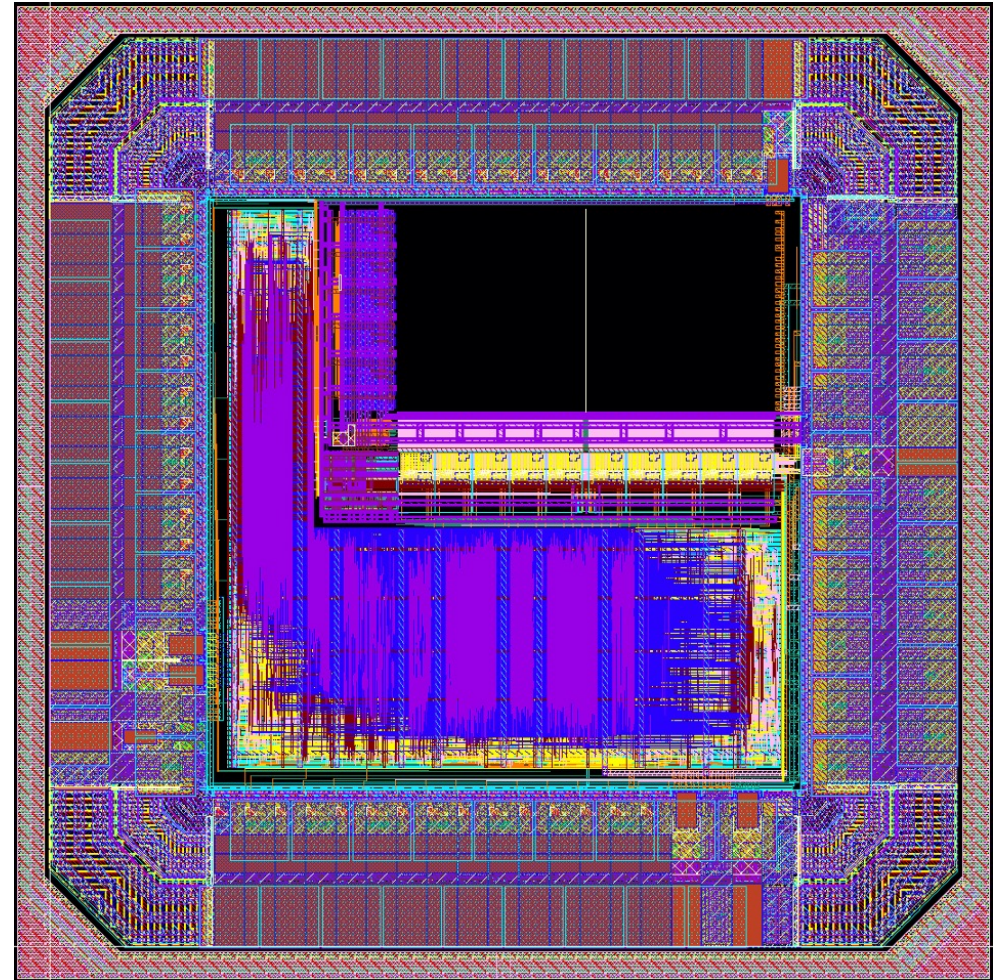


# Example of Back-end Design (Physical Design)

## Routing



## Full-Chip Layout (Courtesy: Bonan Yan's Group)



# From Transistor to Gate

# DRC & LVS